

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar
Title: HYDROPHOBIC FOAMED INSULATORS FOR HIGH DENSITY CIRCUITS
Docket No.: 303.610US1
Filed: August 25, 1999
Examiner: Fetsum Abraham
Serial No.: 09/382,524
Due Date: N/A
Group Art Unit: 2826

MS Amendment


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ Communication Concerning Related Applications (2 pgs.).
- ☒ Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copy of 1 cited document.
- ☒ Authorization to charge Deposit Account 19-0743 in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: 
Atty: David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 31st day of August, 2006.

JUDY DENT

Name


Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

S/N 09/382,524**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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COMMUNICATION CONCERNING RELATED APPLICATION(S)**MS Amendment**

Commissioner for Patents

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Applicant would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10730641 6,953,983	December 8, 2003	1303.041US2	A SEMICONDUCTOR DEVICE COMPRISING LOW DIELECTRIC CONSTANT STI WITH SOI DEVICES
10929632	August 30, 2004	303.681US2	POLYNORBORNENE FOAM INSULATION FOR INTEGRATED CIRCUITS
10931510	September 1, 2004	303.603US2	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES
11216486	August 31, 2005	303.603US3	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES
11275085	December 8, 2005	1303.162US1	INTEGRATED CIRCUIT INSULATORS AND RELATED METHODS
11492255	July 25, 2006	303.681US3	ELECTRONIC APPARATUS HAVING POLYNORBORNENE FOAM INSULATION
11457105	July 12, 2006	303.603US4	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES
11457110	July 12, 2006	303.603US5	PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES


Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

PAUL A. FARRAR

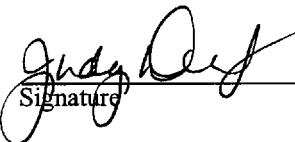
By Applicant's Representatives,

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Date 31 August 2006 By 
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